# imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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## **LNJ447W84RA1**

### Hight Bright Surface Mounting Chip LED

1005 Type

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	55	mW	
Forward current	I <sub>F</sub>	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub> 4		V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Lighting Color

• Amber

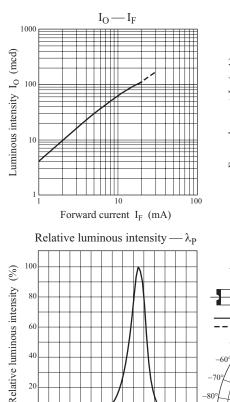
Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

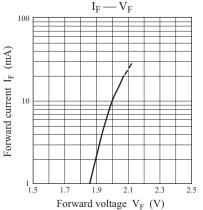
#### Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	Io	$I_F = 5 \text{ mA}$	19.5	30.0	52.4	mcd
Reverse current	I <sub>R</sub>	$V_R = 4 V$			100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 5 \text{ mA}$		1.95	2.30	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 5 \text{ mA}$		595		nm
Dominant emission wavelength *2	λ <sub>d</sub>	$I_F = 5 \text{ mA}$	587	590	597	nm
Spectral half band width	Δλ	$I_F = 5 \text{ mA}$		15		nm

Note) \*1: Measurement tolerance: ±20%

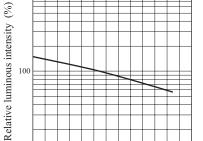
\*2: Measurement tolerance: ±2 nm





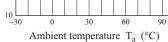
Directive characteristics

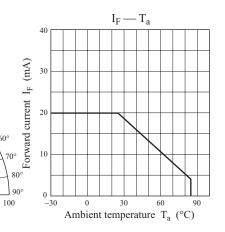
0



Relative luminous intensity — T<sub>a</sub>

1000





Publication date: November 2016

550

Peak emission wavelength  $\lambda_P$  (nm)

600

40

20

ol

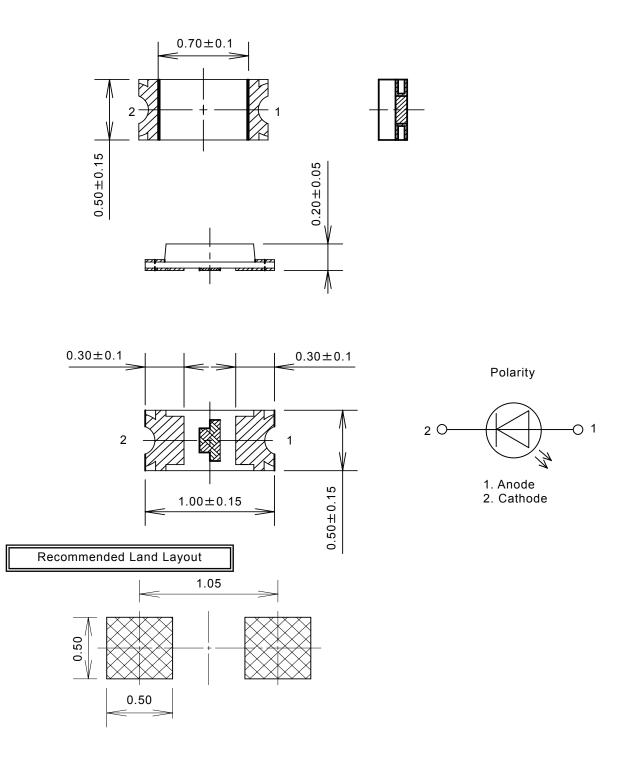
500

Relative luminous intensity (%)

-90

650 100

80 60 40 20 0 20 40 60 80 Package (Unit: mm)



(Note1)Electrode projection is not included in the package dimensions. (Note2)About solder thickness, please examine the products yourself completely. (Recommended thickness : t=0.10 mm~0.15 mm)

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